

B¹ (cont'd)
surface of glide heads using a thermal transducer mounted directly on the air bearing surface.

Please replace the paragraph beginning at page 5, line 18 and ending at page 6, line 6 with the following:

B²
Suitable wafers made from aluminum oxide/titanium carbide composites (AlTiC) are available from a variety of vendors including Sumitomo (Japan), Greenleaf (Saegertown, PA), Minnesota, Mining and Manufacturing (Saint Paul, MN) and Kyocera (Japan). The surfaces of 4.5 inch by 4.5 inch wafers can have a peak-to-valley flatness of less than about 2 μ m. Cutting the wafer into a significant number of glide heads can result in glide heads with significantly reduced peak-to-valley flatness due to the reduced surface area of the glide head relative to the wafer. The contouring of the air-bearing surface onto the smooth surface of the wafer, however, can result in some loss of flatness. Following the contouring of the air bearing surface upon the very smooth and flat surface of the wafer and slicing, the air bearing surface of a glide head can have a flatness of less than about 1 μ inches, preferably less than about 0.5 μ inches, and more preferably less than 0.2 μ inches. Measurements of flatness of a glide head can be performed using optical measuring instruments available from Wyko Corporation, Tucson, Arizona, or from Zyglo Industries, Inc., Portland Oregon.

B³
Please replace the paragraph beginning at page 9, line 24 and ending at page 10, line 2:

B³
Placement of the thermal asperity detector directly on the air bearing surface provides for more sensitive asperity detection. Furthermore, the use of multiple thermal transducers